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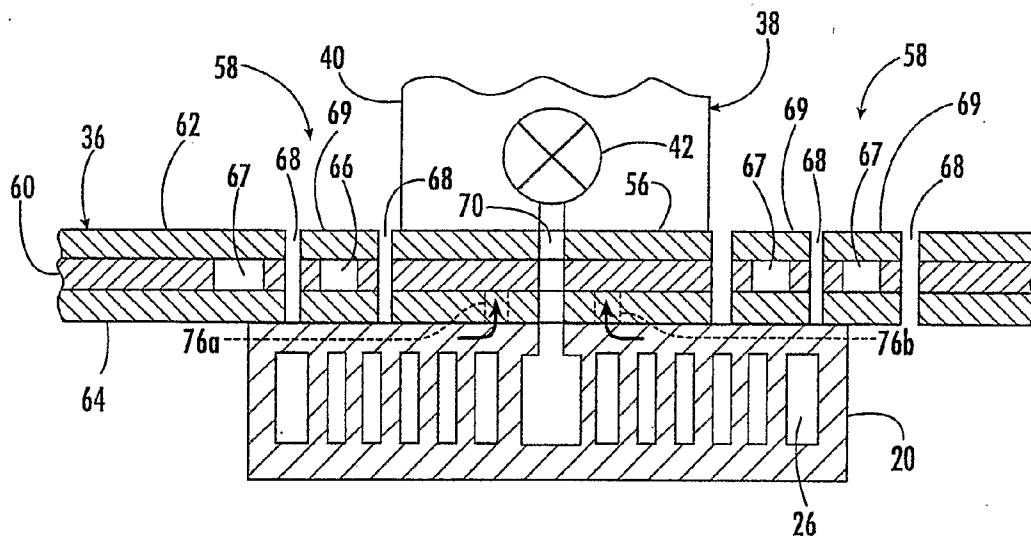
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(54) Title: THERMAL APPARATUS FOR ENGAGING ELECTRONIC DEVICE



(57) Abstract: An apparatus for controlling the temperature of an electronic device utilizes a thermal head attached to a base struc-
ture including an integral isolation arrangement. For example, the isolation arrangement can be formed as a planar spring defined
by slots in the base structure. The base structure has a manifold configured to route refrigerant fluid between the thermal head and
components of a refrigeration system. The isolation arrangement is normally planar but is movable to facilitate engagement of the
thermal head with the electronic device. The isolation arrangement also compensates for variations in the planar orientation of the
electronic device.

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